



NI/CU POLYESTER CONDUCTIVE FABRIC TAPE

Laird's Conductive Fabric Tape 86740 offers exceptional conformability and conductivity for dynamic flex applications. It is constructed of nickel/copper metallized fabric with a conductive pressure sensitive adhesive (PSA). This reliable tape design provides outstanding shielding performance while offering superior abrasion and corrosion resistance under high dynamic flex conditions. The 86740 is a halogen free product and can be supplied in tape or further customized to application by die-cutting or hole punching.

FEATURES

- RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Low surface resistivity of $< 0.05 \Omega/\square$ provides excellent conductivity
- Shielding effectiveness of >75 dB across a wide spectrum of frequencies

MARKETS

- Cabinet applications
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Laptop computers

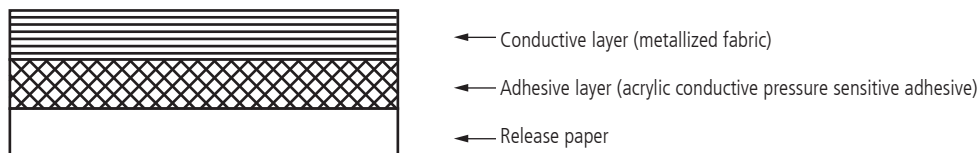


Item	Unit	Value	Test Method
Thickness	mm	0.075 mm $\pm$ 0.01	-
Peel Adhesion	Kgf / 25 mm	>0.8	PSTC 101*
Shear Adhesion			
	at R.T.	Hrs	>72 PSTC 107#
	at 80°C	Hrs	>5 PSTC 107#
Tensile Strength	Kgf / 25 mm	>7.5	
Operation Temperature	°C	0-80	
Surface Resistivity (Fabric Side)	$\Omega/\square$	<0.05	ASTM F390
Z-axial Resistance	Ω	<0.03	
Shielding Effectiveness*			ASTM D4935
	at 100 MHz	dB	75
	at 1GHz	dB	80
Package Dimensions (Max. Width: 1000 mm)	M	W: Dimension by Customer Spec L: Standard Length of 20 M	
Shelf Life (Under 23°C/65% R.H.)		Six Months	

*:Test Method A, dwell time 30 min. #:Contact area 25 mm by 25 mm +:Typical value

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COMPOSITION OF PRODUCT



APPLICATION TECHNIQUES

1. Bond strength is dependent upon the amount of adhesive-to-surface contact developed. Firm application pressure develops better adhesive contact & thus improves bond strength.
2. To obtain optimum adhesion, the bonding surfaces must be clean, dry and well unified. A typical surface cleaning solvent is isopropyl alcohol. Use proper safety precautions for handling solvents.
3. Ideal tape application temperature range is 21°C to 38°C. Initial tape application to surfaces at temperatures below 10°C is not recommended because the adhesive becomes too firm to adhere readily. However, once properly applied, low temperature holding is generally satisfactory.